
Velektronik

Platform for Trustworthy Electronics



Project Overview

■ ZEUS¹

- National funding call dedicated to trustworthy electronics
- Funded by Federal Ministry of Education and Research (BMBF)²
- 14 projects, 83M€ total budget, 74% average funding rate

■ VE-Velektronik

- 15 partners: Fraunhofer, Leibnitz, edacentrum
- 6M€, 2021 – 2024
- <https://www.velektronik.de/en/>

¹ <https://www.elektronikforschung.de/foerderung/bekanntmachungen/zeus> (only in German)

² https://www.bmbf.de/bmbf/en/home/home_node.html

Project Overview

■ Goals

- Identify challenges and solutions within electronics value chain
- Provide a national platform to connect stakeholders

■ Tools

- Yearly national symposium on trustworthy electronics¹
 - March 9th - 10th 2022
 - Digital, ~200 participants
- Reference paper on trustworthy electronics²
- Workshops on chip design, manufacturing, and analysis

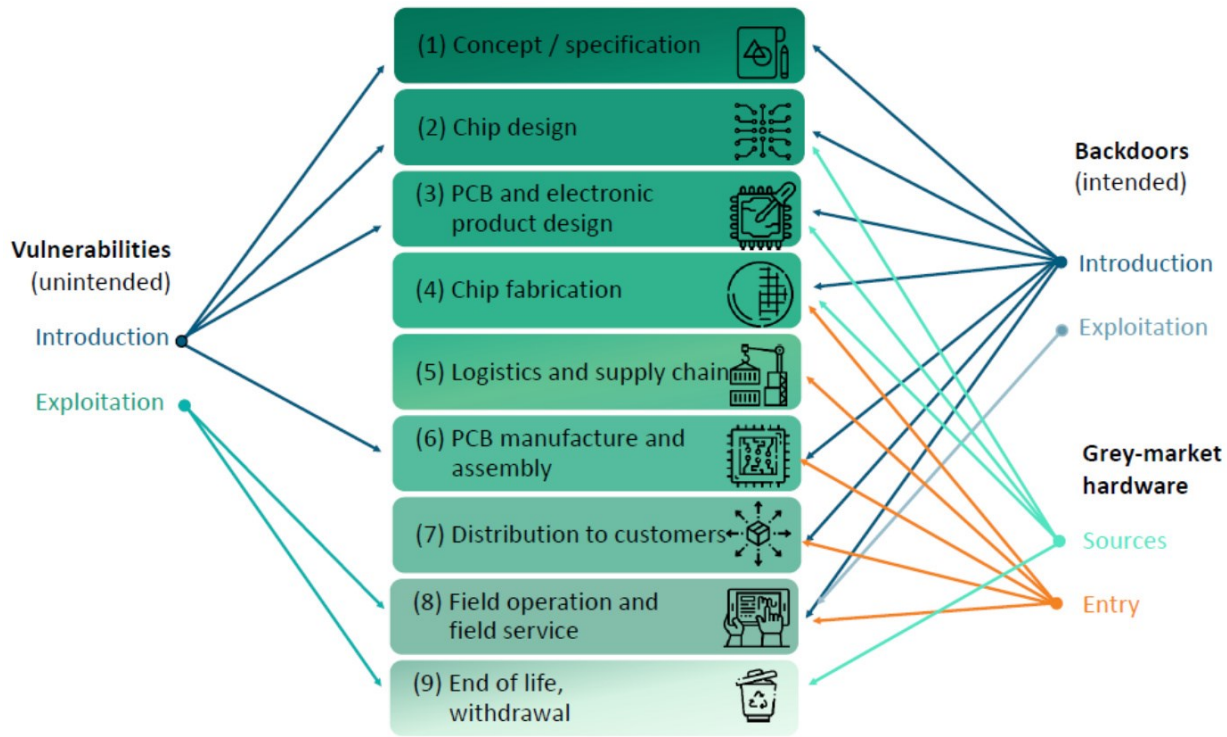
¹ <https://www.elektronikforschung.de/fokusthemen/vertrauenswuerdigkeit/digitale-fachkonferenz-vertrauenswuerdige-elektronik-2022> (only in German)

² https://www.velektronik.de/wp-content/uploads/2022/09/Referenzpapier_Vertrauenswuerdige_Elektronik.pdf (English version available)

Definition: Trustworthy Electronics

1. The hardware must meet **high levels of quality and reliability**.
 - Reliable operation in the field over its full lifetime.
2. The hardware must comply to a **known and complete specification**.
 - Functionality cannot be altered from the specification.
3. The hardware must be sufficiently **hardened against attacks**.
 - Mechanisms to ensure security and avoid vulnerabilities.

Value Chain and Trust Issues



Setting Priorities

- Risk analysis
 - **Severity** – prospective damage
 - **Probability of occurrence** – practical relevance
 - **Benefit / cost ration** – attractiveness for adversaries
- Priorities
 - Three levels: high, medium, low
 - Assessment by experts within Velektronik
 - Reviewed by representatives from research and industry

High-Priority Threats

- **Unintentional vulnerabilities** introduced in **early design steps** and exploited in the field.
- **Intentional backdoors** such as malicious / implant ICs and firmware introduced in **late value chain steps** (e.g. during PCB assembly and logistics).
- **Grey market hardware** through overproduction, use of rejects, and illegal recycling, which infiltrates the value chain at **late value chain steps**.

Assessing Solutions

■ Helpful criteria

- Is a high-priority threat addressed?
- Are significant improvements achieved?
- What are the necessary expenditures?

■ ZEUS project landscape

- All high-priority threats are addressed
- Least coverage: backdoors in late value chain steps (PCB, assembly, distribution)
- No coverage: backdoors in early value chain steps (spec, standards, chip design)

Outlook

■ Open questions

- Definition precise and comprehensive enough?
- How to quantify and measure trustworthiness (in each value chain step)?
- How will trust issues and threats develop?

■ Specific topics

- Open(-source) hardware – instruction sets, EDA tools, PDKs, chip components
- Zero trust – technological vs. organizational measures

■ Next national symposium

- Planned for May 2023 in Hannover

Thank you for your attention!

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